



Part No. 97-AQ132D - 132 Pin PQFP to Amp Socket PGA Footprint

FEATURES:

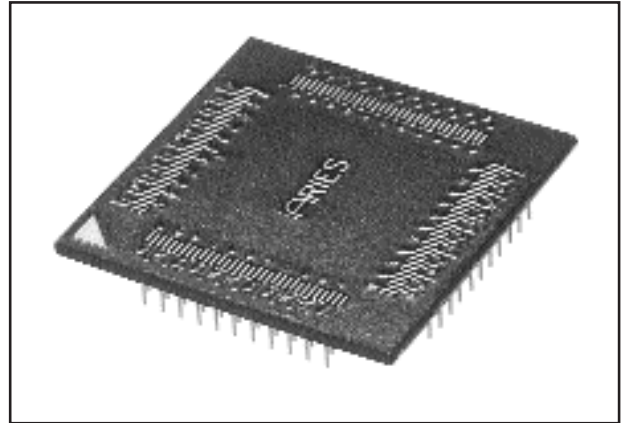
- Convert surface mount PQFP packages to an Amp interstitial PGA footprint.
- Reduce costs by using less expensive PQFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for panelized form or for mounting of consigned chips.

SPECIFICATIONS:

- Body material is FR-4, .062 [1.58] thick, with 1 ounce minimum Copper traces.
- Pads are bare Copper protected with ENIG (Immersion Gold over Electroless Nickel) to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling.
- Pin is Brass Alloy 360 1/2 hard per UNS C36000 ASTM-B16-00.
- Pin plating is Tin/Lead 93/7 per ASTM B 545 over 100μ [2.54μm] Nickel.
- Operating temperature=221°F [105°C].

MOUNTING CONSIDERATIONS:

- Suggested PCB hole size=.028 ± .003 [.71 ± .08] dia.
- Will plug into existing PGA footprint with matching pad assignments.



Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and finishes can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.

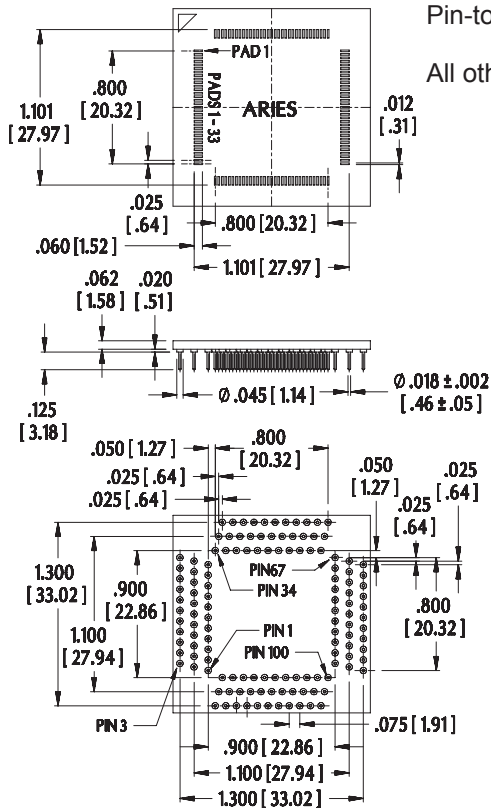
ORDERING INFORMATION

Specify Part No. 97-AQ132D

-OR-

97-AQ132D-P for panelized form
when ordering

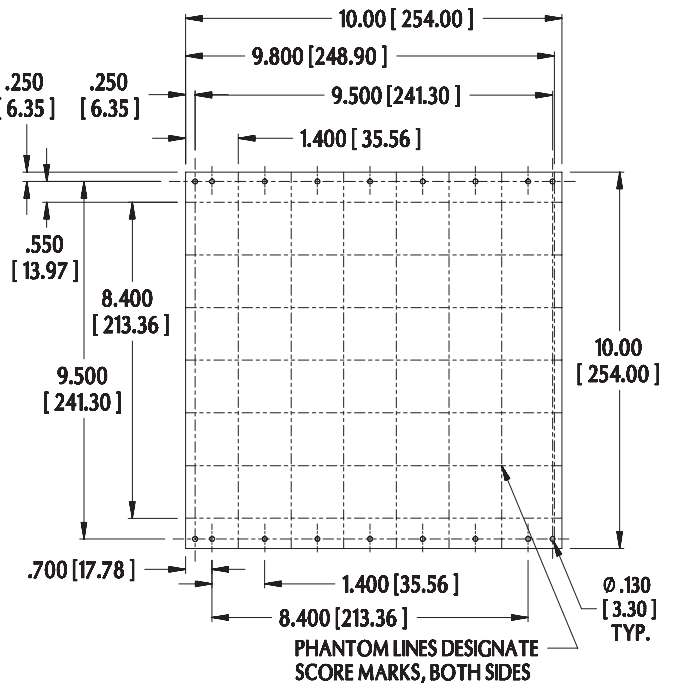
ALL DIMENSIONS: INCHES [MILLIMETERS]



Tolerances:

- Row-to-row: ± .003 [.08]
- Pin-to-pin: ± .003 [.08]
- non-cumulative
- All others: ± .005 [.08] unless otherwise specified

PANELIZED FORM (42 per Panel)



Bristol, PA USA
TEL: (215) 781-9956
FAX: (215) 781-9845



18022
REV. H